

# 74ABT08

## Quad 2-input AND gate

Rev. 2 — 14 March 2014

Product data sheet

### 1. General description

The 74ABT08 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT08 is a quad 2-input AND gate.

### 2. Features and benefits

- Latch-up protection exceeds 500 mA per JEDEC78B class II level A
- ESD protection:
  - ◆ HBM JEDEC22-A114F exceeds 2000 V
  - ◆ MM JEDEC22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to +85 °C

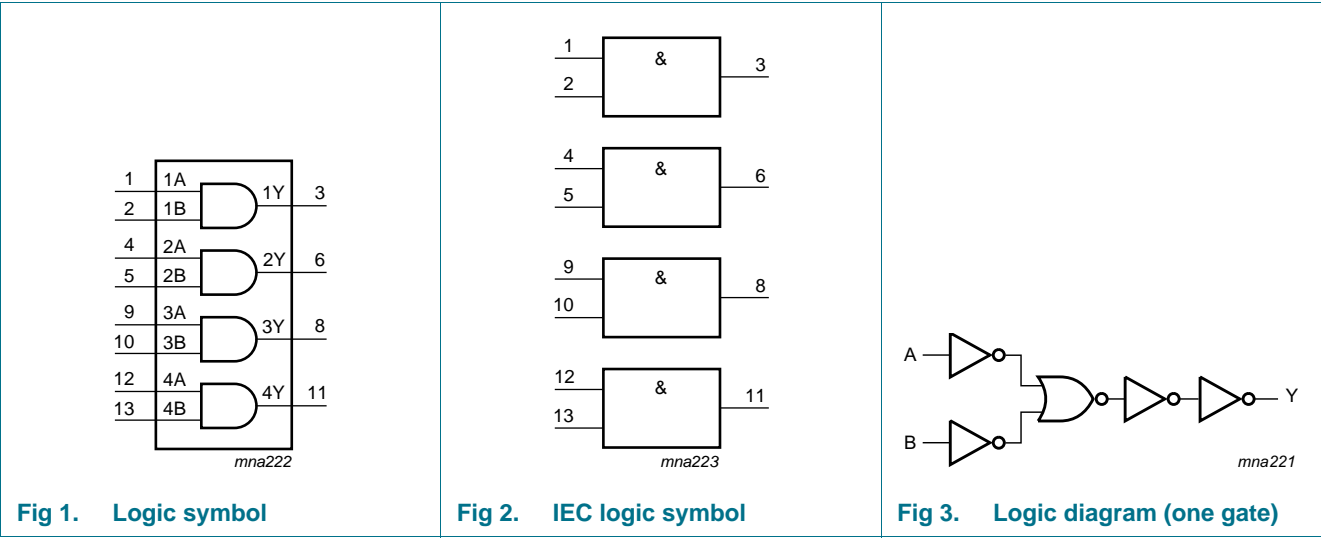
### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74ABT08N	-40 °C to +85 °C	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
74ABT08D	-40 °C to +85 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74ABT08DB	-40 °C to +85 °C	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74ABT08PW	-40 °C to +85 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1

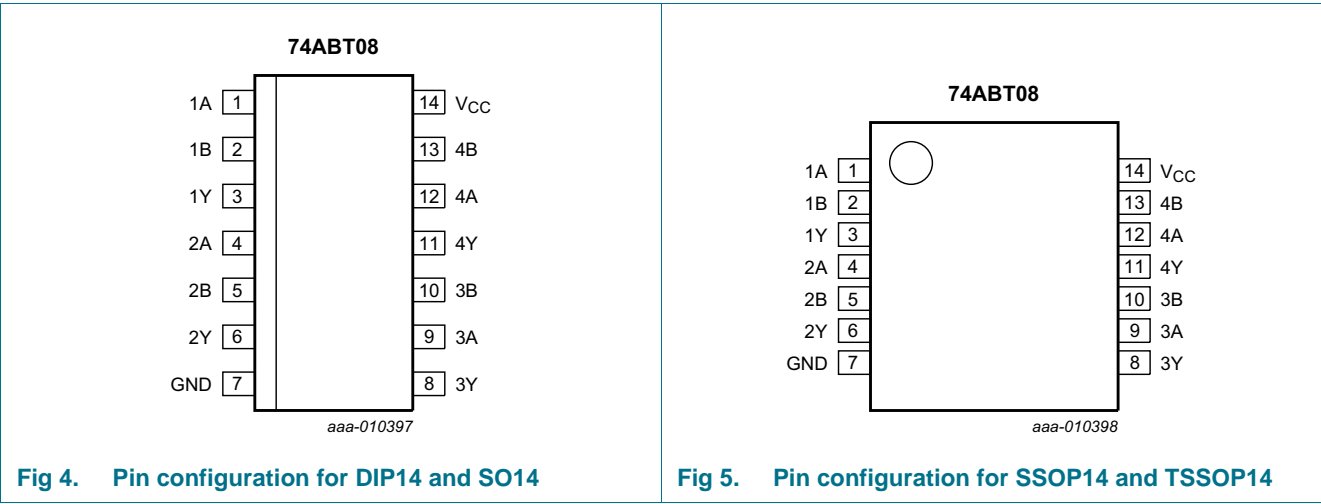


4. Functional diagram



5. Pinning information

5.1 Pinning



## 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A to 4A	1, 4, 9, 12	data input
1B to 4B	2, 5, 10, 13	data input
1Y to 4Y	3, 6, 8, 11	data output
GND	7	ground (0 V)
V <sub>CC</sub>	14	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Input		Output
nA	nB	nY
L	X	L
X	L	L
H	H	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		−0.5	+7.0	V
V <sub>I</sub>	input voltage		<sup>[1]</sup> −1.2	+7.0	V
V <sub>O</sub>	output voltage	output HIGH or LOW	<sup>[1]</sup> −0.5	+5.5	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	−18	-	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < 0 V	−50	-	mA
I <sub>O</sub>	output current	output in LOW-state	-	40	mA
T <sub>j</sub>	junction temperature		<sup>[2]</sup> -	150	°C
T <sub>stg</sub>	storage temperature		−65	+150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

## 8. Recommended operating conditions

**Table 5. Operating conditions**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		4.5	-	5.5	V
$V_I$	input voltage		0	-	$V_{CC}$	V
$V_{IH}$	HIGH-level input voltage		2.0	-	-	V
$V_{IL}$	LOW-level input voltage		-	-	0.8	V
$I_{OH}$	HIGH-level output current		-15	-	-	mA
$I_{OL}$	LOW-level output current		-	-	20	mA
$\Delta t/\Delta V$	input transition rise and fall rate		0	-	5	ns/V
$T_{amb}$	ambient temperature	in free air	-40	-	+85	°C

## 9. Static characteristics

**Table 6. Static characteristics**

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		Unit
			Min	Typ	Max	Min	Max	
$V_{IK}$	input clamping voltage	$V_{CC} = 4.5\text{ V}$ ; $I_{IK} = -18\text{ mA}$	-1.2	-0.9	-	-1.2	-	V
$V_{OH}$	HIGH-level output voltage	$V_{CC} = 4.5\text{ V}$ ; $I_{OH} = -15\text{ mA}$ ; $V_I = V_{IL}$ or $V_{IH}$	2.5	2.9	-	2.5	-	V
$V_{OL}$	LOW-level output voltage	$V_{CC} = 4.5\text{ V}$ ; $I_{OL} = 20\text{ mA}$ ; $V_I = V_{IL}$ or $V_{IH}$	-	0.35	0.5	-	0.5	V
$I_I$	input leakage current	$V_{CC} = 5.5\text{ V}$ ; $V_I = \text{GND}$ or $5.5\text{ V}$	-	$\pm 0.01$	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$
$I_{OFF}$	power-off leakage current	$V_{CC} = 0\text{ V}$ ; $V_I$ or $V_O \leq 4.5\text{ V}$	-	$\pm 5.0$	$\pm 100$	-	$\pm 100$	$\mu\text{A}$
$I_{CEX}$	output high leakage current	HIGH-state; $V_O = 5.5\text{ V}$ ; $V_{CC} = 5.5\text{ V}$ ; $V_I = \text{GND}$ or $V_{CC}$	-	5.0	50	-	50	$\mu\text{A}$
$I_O$	output current	$V_{CC} = 5.5\text{ V}$ ; $V_O = 2.5\text{ V}$ <a href="#">[1]</a>	-50	-75	-180	-50	-180	mA
$I_{CC}$	supply current	$V_{CC} = 5.5\text{ V}$ ; $V_I = \text{GND}$ or $V_{CC}$	-	2	50	-	50	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	per input pin; $V_{CC} = 5.5\text{ V}$ ; one input at $3.4\text{ V}$ ; other inputs at $V_{CC}$ or GND <a href="#">[2]</a>	-	0.25	500	-	500	$\mu\text{A}$
$C_I$	input capacitance	$V_I = 0\text{ V}$ or $V_{CC}$	-	3	-	-	-	pF

[1] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[2] This is the increase in supply current for each input at 3.4 V.

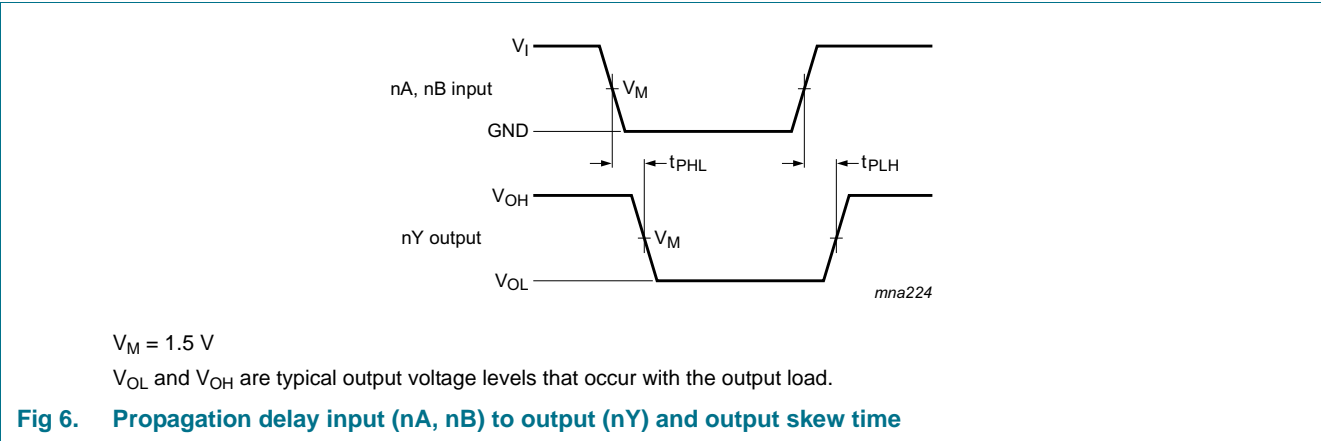
10. Dynamic characteristics

Table 7. Dynamic characteristics  
GND = 0 V; for test circuit, see Figure 7.

Symbol	Parameter	Conditions	25 °C; V <sub>CC</sub> = 5.0 V			−40 °C to +85 °C; V <sub>CC</sub> = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	
t <sub>PLH</sub>	LOW to HIGH propagation delay	nA, nB to nY; see Figure 6	1.0	2.4	3.4	1.0	4.0	ns
t <sub>PHL</sub>	HIGH to LOW propagation delay	nA, nB to nY; see Figure 6	1.0	1.9	2.8	1.0	3.0	ns
t <sub>sk(o)</sub>	output skew time	[1]	-	0.4	0.5	-	0.5	ns

[1] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

11. Waveforms



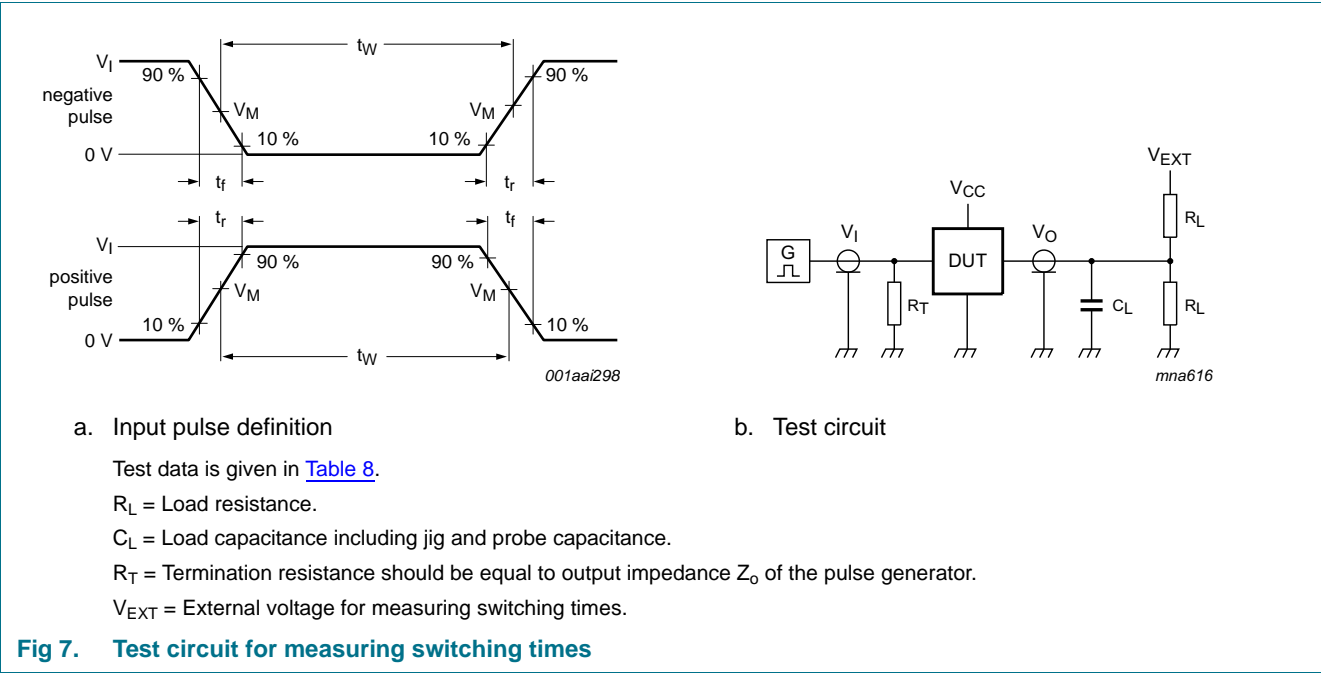


Fig 7. Test circuit for measuring switching times

Table 8. Test data

Input				Load		$V_{EXT}$
$V_I$	$f_i$	$t_W$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$
3.0 V	1 MHz	500 ns	$\leq 2.5$ ns	50 pF	500 $\Omega$	open

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil) SOT27-1

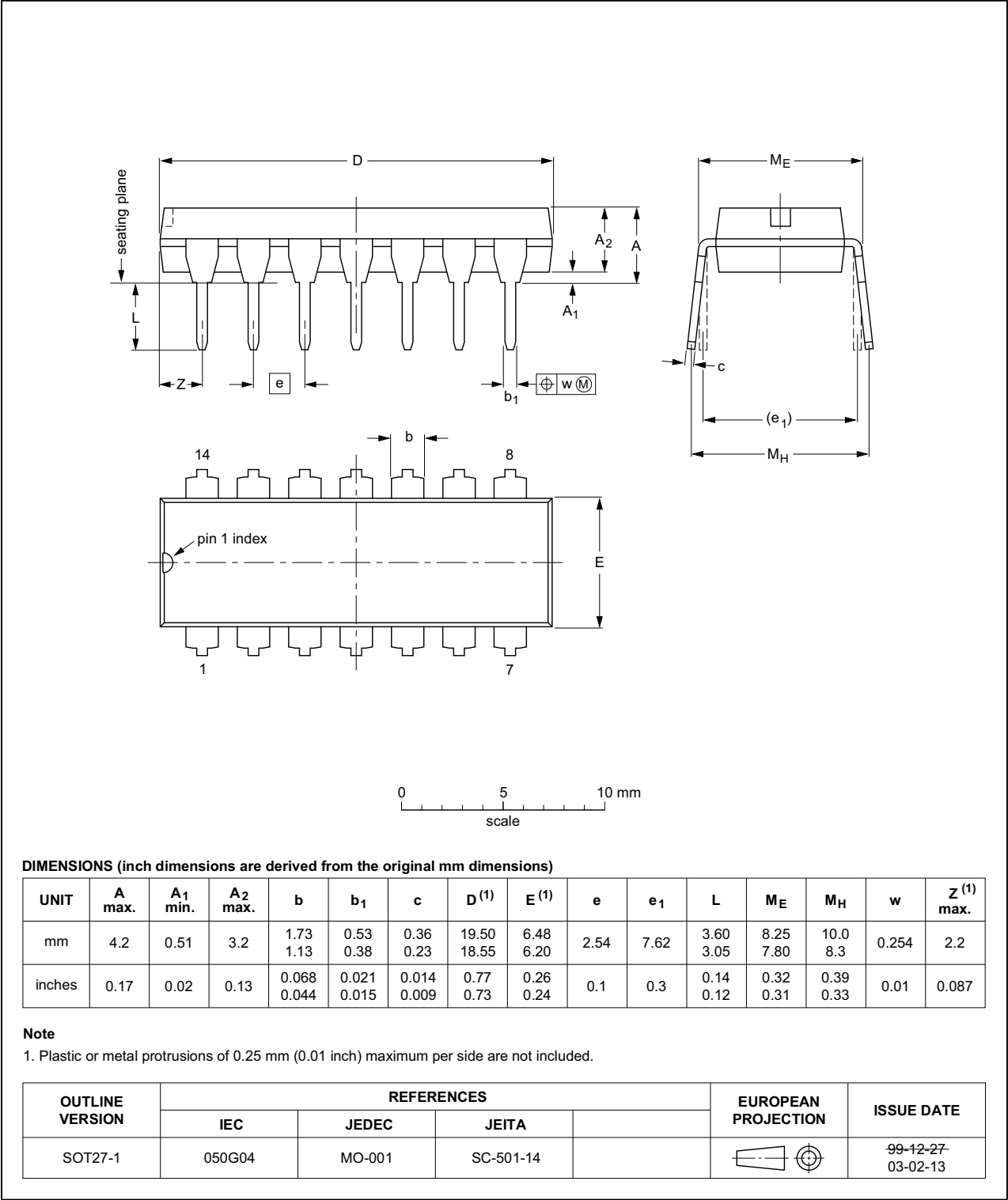


Fig 8. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

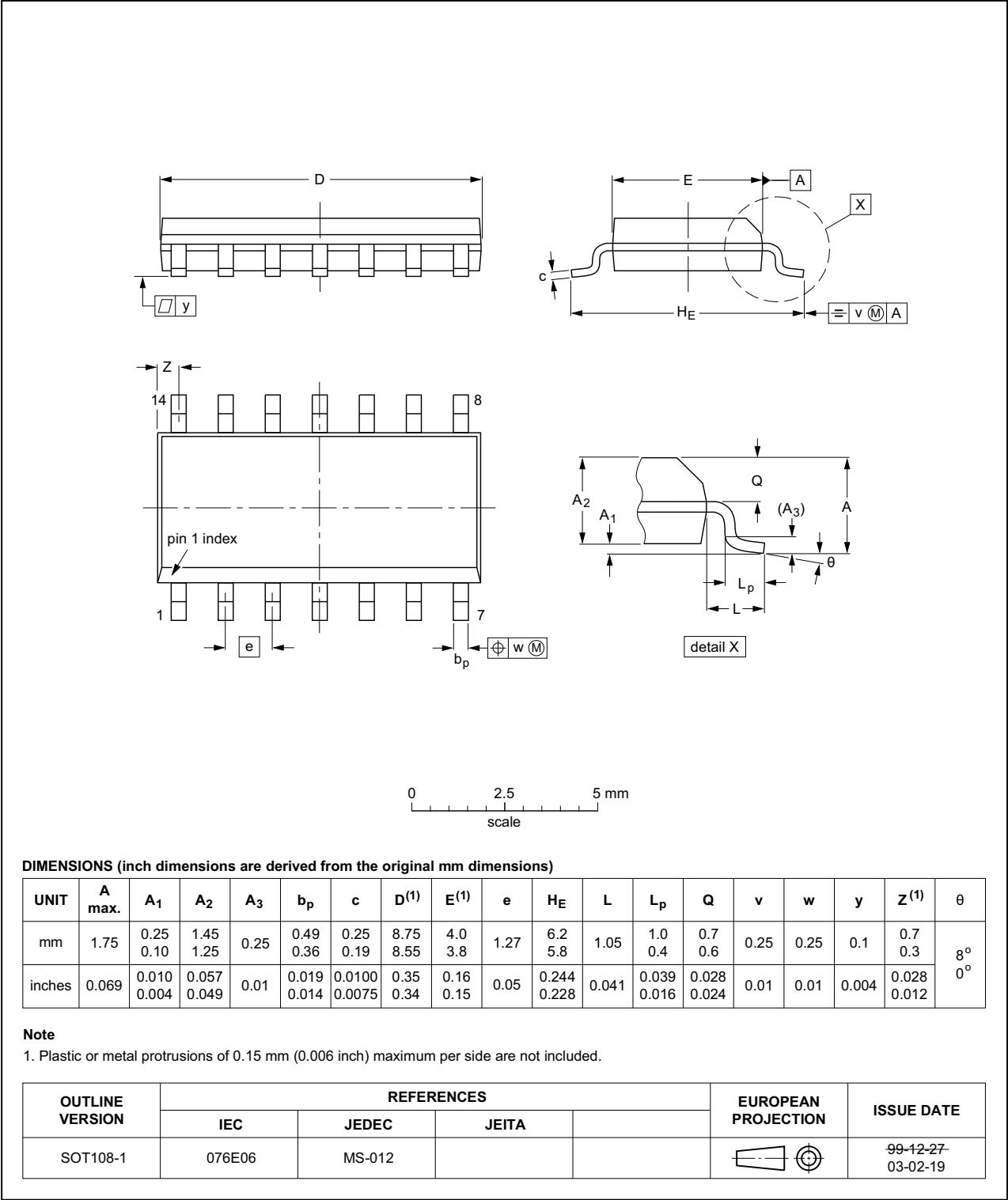


Fig 9. Package outline SOT108-1 (SO14)



SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

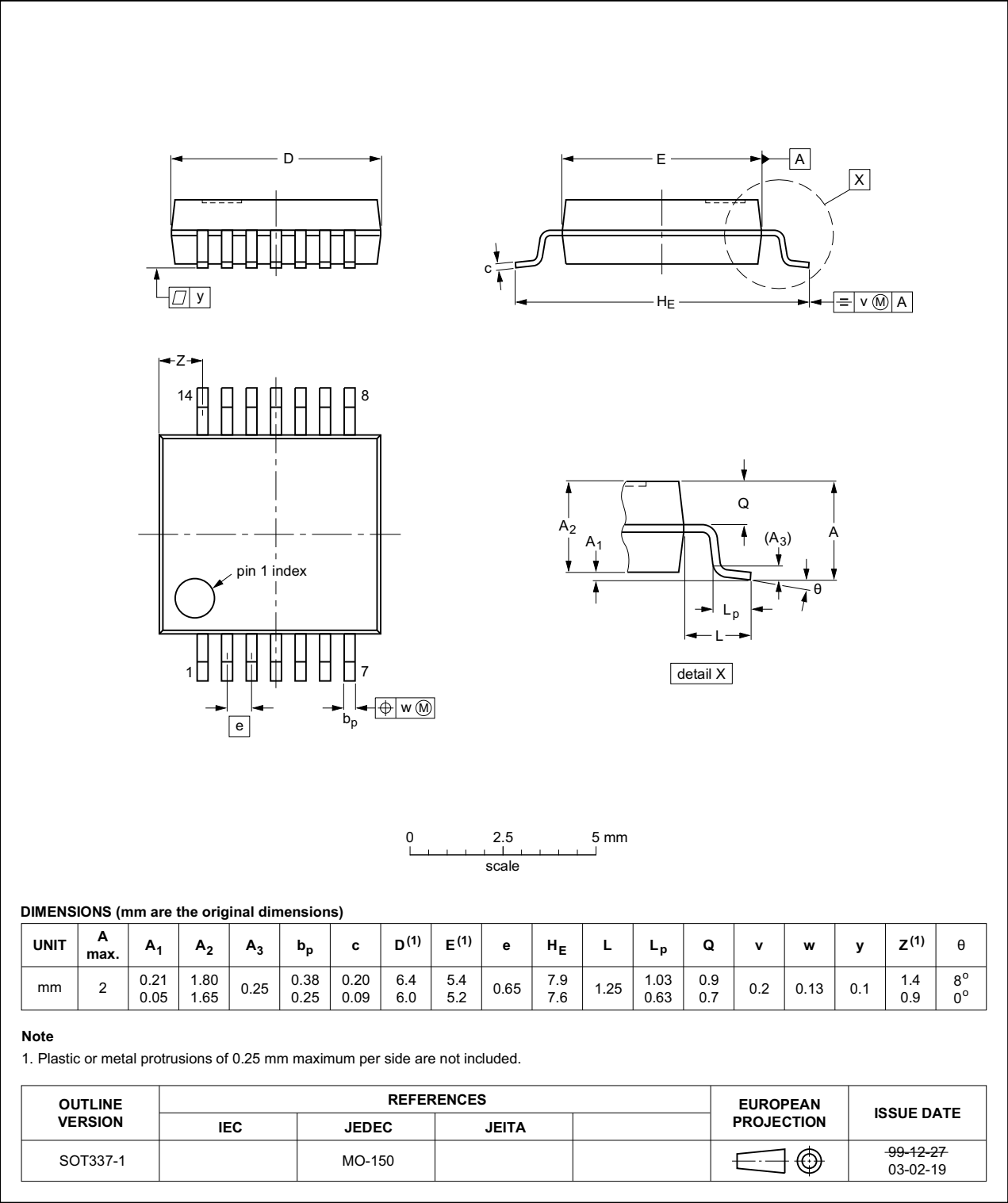


Fig 10. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

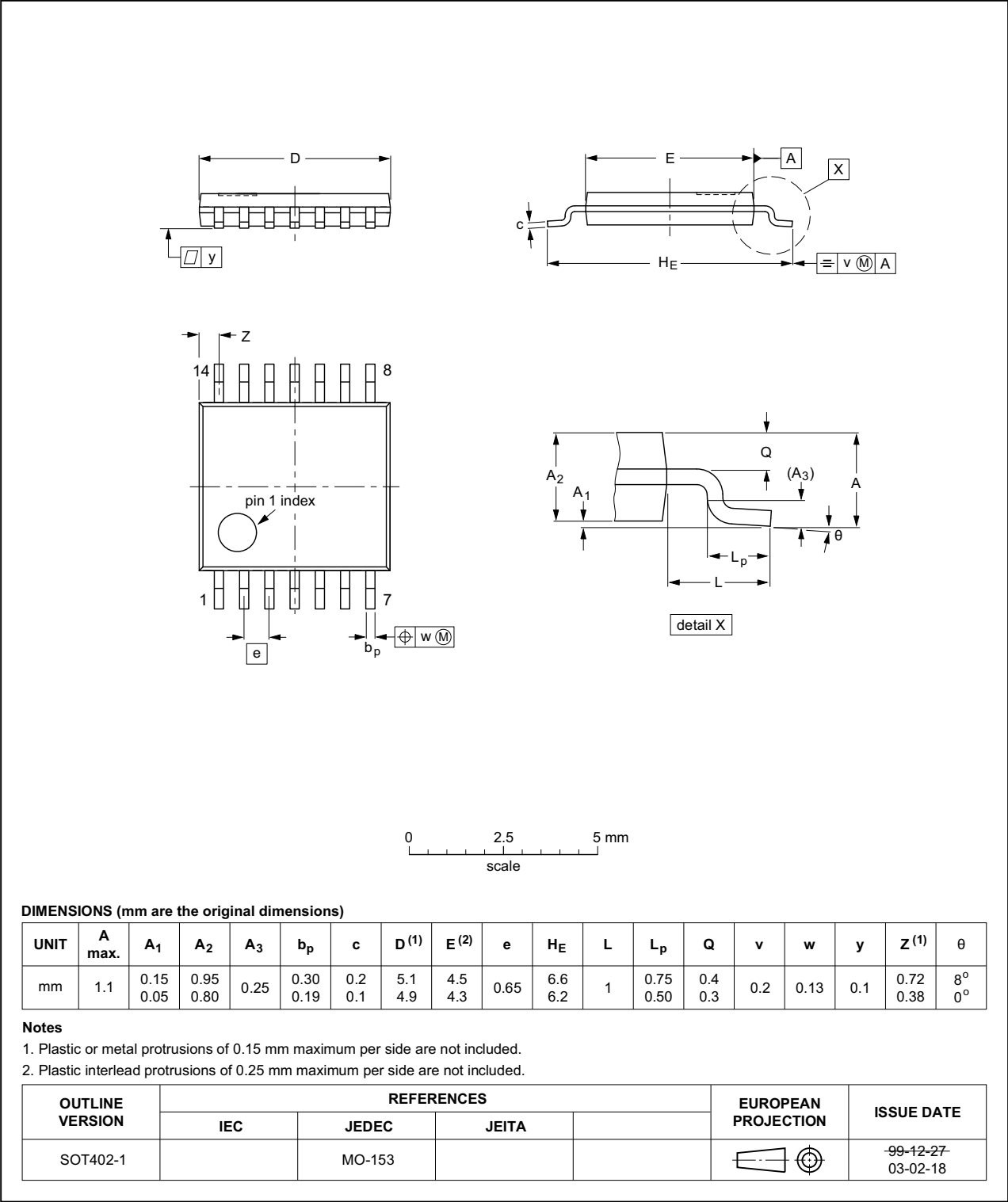


Fig 11. Package outline SOT402-1 (TSSOP14)

## 13. Abbreviations

Table 9. Abbreviations

Acronym	Description
BiCMOS	Bipolar Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ABT08 v.2	20140314	Product data sheet	-	74ABT08 v.1
Modifications:	<ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>Legal texts have been adapted to the new company name where appropriate.</li></ul>			
74ABT08 v.1	19950918	Product specification	-	-

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### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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## 17. Contents

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<b>1</b>	<b>General description</b> .....	<b>1</b>
<b>2</b>	<b>Features and benefits</b> .....	<b>1</b>
<b>3</b>	<b>Ordering information</b> .....	<b>1</b>
<b>4</b>	<b>Functional diagram</b> .....	<b>2</b>
<b>5</b>	<b>Pinning information</b> .....	<b>2</b>
5.1	Pinning .....	2
5.2	Pin description .....	3
<b>6</b>	<b>Functional description</b> .....	<b>3</b>
<b>7</b>	<b>Limiting values</b> .....	<b>3</b>
<b>8</b>	<b>Recommended operating conditions</b> .....	<b>4</b>
<b>9</b>	<b>Static characteristics</b> .....	<b>4</b>
<b>10</b>	<b>Dynamic characteristics</b> .....	<b>5</b>
<b>11</b>	<b>Waveforms</b> .....	<b>5</b>
<b>12</b>	<b>Package outline</b> .....	<b>7</b>
<b>13</b>	<b>Abbreviations</b> .....	<b>11</b>
<b>14</b>	<b>Revision history</b> .....	<b>11</b>
<b>15</b>	<b>Legal information</b> .....	<b>12</b>
15.1	Data sheet status .....	12
15.2	Definitions .....	12
15.3	Disclaimers .....	12
15.4	Trademarks .....	13
<b>16</b>	<b>Contact information</b> .....	<b>13</b>
<b>17</b>	<b>Contents</b> .....	<b>14</b>

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